

APPLICABLE STANDARD				
Rating	Operating Temperature Range	-55 °C to 85 °C ⁽¹⁾	Storage Temperature Range	-10 °C to 60 °C ⁽²⁾
	Voltage	50 V AC	Storage Humidity Range	Relative humidity 85% max (Not dewed)
	Current	0.7 A	Operating Humidity Range	

SPECIFICATIONS

ITEM	TEST METHOD	REQUIREMENTS	QT	AT
CONSTRUCTION				
General Examination	Visually and by measuring instrument.	According to drawing.	x	x
Marking	Confirmed visually.		x	x
ELECTRIC CHARACTERISTICS				
Contact Resistance	100 mA(DC or 1000Hz)	70mΩ MAX.	x	—
Insulation Resistance	100 V DC.	100 MΩ MIN.	x	—
Voltage Proof	150 V AC for 1 min.	No flashover or breakdown.	x	x
MECHANICAL CHARACTERISTICS				
Insertion and Withdrawal Forces	Measured by applicable connector.	Insertion Force: 62 N MAX. Withdrawal Force: 6.2 N MIN.	x	—
Mechanical Operation	50 times insertions and extractions.	① Contact Resistance : 80mΩ MAX. ② No damage, crack and looseness of parts.	x	—
Vibration	Frequency 10 to 55 to 10Hz, approx 5min Single amplitude : 0.75 mm, 10 cycles for 3 axial directions.	① No electrical discontinuity of 1 μs. ② No damage, crack and looseness of parts.	x	—
Shock	490 m/s ² , duration of pulse 11 ms at 3 times for 3 both axial directions.		x	—
ENVIRONMENTAL CHARACTERISTICS				
Damp Heat (Steady state)	Exposed at 40±2 °C, 90 ~ 95 %, 96 h.	① Contact Resistance : 80mΩ MAX. ② Insulation Resistance:100 MΩ MIN.	x	—
Rapid Change of Temperature	Temperature -55 → +85 °C Time 30 → 30 min. under 5 cycles. (Relocation time to chamber : within 2~3 MIN)	③ No damage, crack and looseness of parts.	x	—
Cold	Exposed at -55°C, 96 h	① Contact Resistance : 80mΩ ② No damage, crack and looseness of parts.	x	—
Dry Heat	Exposed at 85°C, 96 h		x	—
Sulfur Dioxide	Exposed at 25±2°C, 75±5%RH, 25 PPM for 96 h. (Test standard: JIS C 60068)	① No defect such as corrosion which impairs the function of connector. ② Contact Resistance : 80mΩ	x	—
Resistance to Soldering Heat	1)Reflow soldering : Peak TMP : 260°C MAX Reflow TMP: 220°C MIN for 60sec 2) Soldering irons : 360°C MAX. for 5 sec.	No deformation of case of excessive looseness of the terminal.	x	—
Solderability	Soldered at solder temperature 245±3°C for immersion duration, 3 sec.	A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed.	x	—

COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
1	DIS-F-007685	AH. EDASHIGE	KN. SHIBUYA	14. 10. 29

REMARKS ⁽¹⁾ Include temperature rise caused by current-carrying. ⁽²⁾ "STORAGE" means a long-term storage state for the unused product before assembly to PCB. Decapitalized Unless otherwise specified, refer to JIS-C-5402.	APPROVED	HS. OKAWA	14. 09. 02
	CHECKED	KN. SHIBUYA	14. 09. 02
	DESIGNED	AH. EDASHIGE	13. 11. 15
	DRAWN	AH. EDASHIGE	13. 11. 15

Note QT:Qualification Test AT:Assurance Test X:Applicable Test DRAWING NO. ELC4-352599-00

HRS	SPECIFICATION SHEET	PART NO.	FX22-80P-0. 5SH		
	HIROSE ELECTRIC CO., LTD.	CODE NO.	CL572-3004-2-00		1/1

